

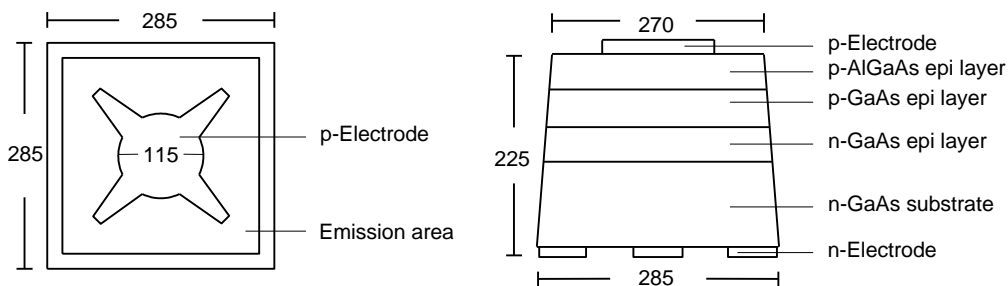
### ■ Features :

- AlGaAs/GaAs Wafer
- Good Spectral Matched to Si Detector

### ■ Typical Applications :

- Remote Controller
- Peripheral Device
- Photo Coupler
- Photo Interrupter

### ■ Outline Dimensions : (Unit: $\mu\text{m}$ )



### ■ Physical Structure :

Chip dimension	Chip size	285 $\mu\text{m}$ x 285 $\mu\text{m}$
	Thickness	225 $\mu\text{m}$
	Emission area	270 $\mu\text{m}$
	Bonding pad	115 $\mu\text{m}$
Electrode	Top: P (anode)	Gold
	Backside: N (cathode)	Gold alloy
Surface condition	Frosted	

### ■ Electro-Optical Characteristics : ( $T_a = 25^\circ\text{C}$ )

Parameter	Symbol	Condition	Min.	Typ.	Max.	Unit
Forward Voltage	$V_F$	$I_F = 20 \text{ mA}$	-	1.22	1.40	V
		$I_F = 100 \text{ mA}$	-	1.37	1.55	
Reverse Voltage	$V_R$	$I_R = 10 \text{ uA}$	5	-	-	V
Wavelength	$\lambda_p$	$I_F = 20 \text{ mA}$	-	940	-	nm
Spectral width at half height	$\Delta\lambda$	$I_F = 20 \text{ mA}$	-	50	-	nm
*1 Radiant Power	$P_o$	$I_F = 20 \text{ mA}$	0.50	1.00	-	mW

■ Typical Electro-Optical Characteristics Curve:

Fig 1. Forward Current vs. Forward Voltage

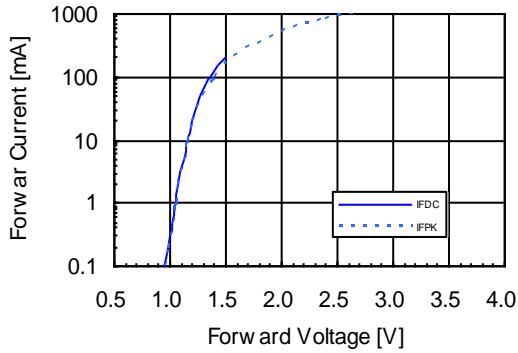


Fig 2. Relative Radiant Power vs. Wavelength

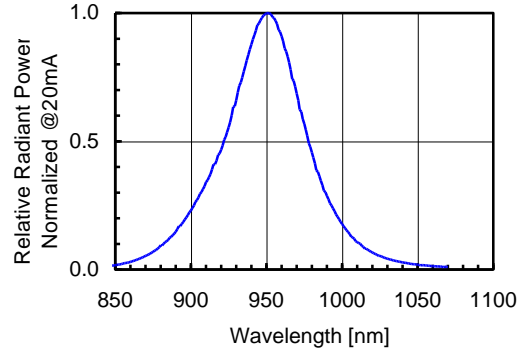


Fig 3. Relative Radiant Power vs. Forward DC Current

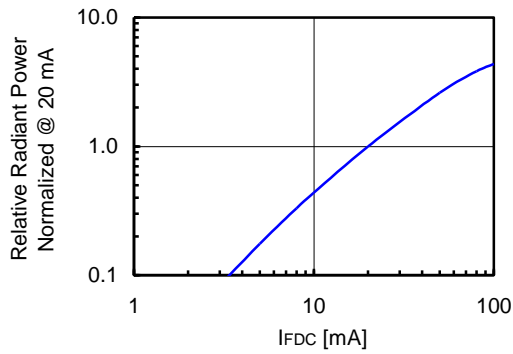


Fig 4. Relative Radiant Power vs. Forward Peak Current

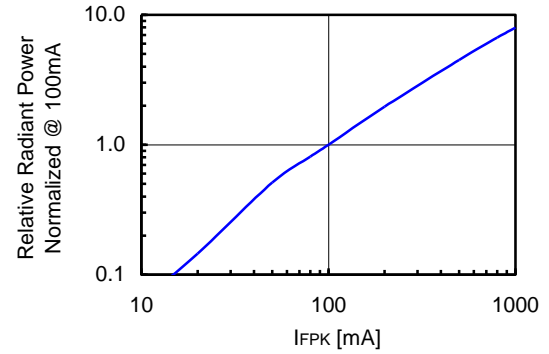


Fig 5. Forward DC Voltage vs. Temperature

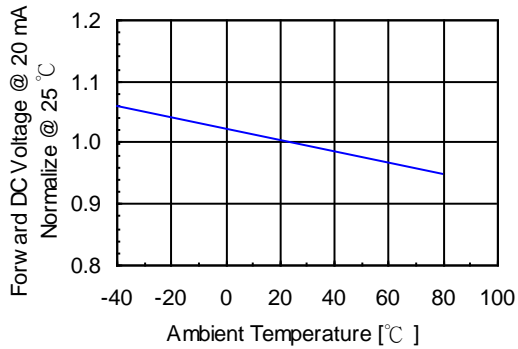


Fig 6. Relative Radiant Power vs. Temperature

